

Appl. No. 10/644,644
Amdt. dated [insert date]
Preliminary Amendment

PATENT

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

- 1.-51. (Cancelled)
52. (New) A method for forming multilayered substrates, the method comprising:
 - providing a donor substrate comprising an overlying film of material to be detached;
 - coupling the film of material from the donor substrate to a transfer substrate;
 - releasing the film of material from the donor substrate, while maintaining attachment to the transfer substrate; and
 - coupling the film of material on the transfer substrate to a handle substrate;
 - transferring the film of material from the transfer substrate to the handle substrate to free the film of material from the transfer substrate while providing the film of material on the handle substrate.
53. (New) The method of claim 52 wherein the transfer substrate temporarily holds the film of material before the film of material has been released using a controlled cleaving action.
54. (New) The method of claim 52 wherein the transfer substrate couples to a top surface of the film of material.
55. (New) The method of claim 52 wherein the transfer substrate couples to an implanted surface of the film of material.

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56. (New) The method of claim 52 wherein the coupling is provided using a bonding technique selected from electrostatic, adhesive, and interatomic.

57. (New) The method of claim 52 wherein the transfer substrate can be made of a material selected from a dielectric material or a conductive material.

58. (New) The method of claim 57 wherein the dielectric material is selected from quartz, glass, sapphire, silicon nitride, and silicon dioxide.

59. (New) The method of claim 57 wherein the conductive material is selected from silicon, silicon carbide, polysilicon, group III/V materials, and metal.

60. (New) The method of claim 52 wherein the transfer material comprises a plastic material.

61. (New) The method of claim 60 wherein the plastic material is selected from a polyimide-based material.

62. (New) The method of claim 52 wherein the film of material has been formed using a controlled cleaving action before the coupling of the film of material on the transfer substrate.

63. (New) The method of claim 52 wherein the film of material on the donor substrate has been detached but not removed.

64. (New) The method of claim 52 further comprising subjecting the film of material on the transfer substrate to a first process.

65. (New) The method of claim 52 further comprising subjecting the film of material on the transfer substrate to a second process.